Specification of Thermoelectric Module TEFC1-22920

Description

The 229 couples, 12.2 mm × 55.4 mm size module is a single stage module which is made of selected high performance ingot to achieve superior cooling performance and greater delta T up to 70 °C, designed for superior cooling and heating up to 100/200 °C requirement. It has higher cooling efficiency than normal type module. If higher operation or processing temperature is required, please specify, we can design and manufacture the custom made module according to your special requirements.

Features

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

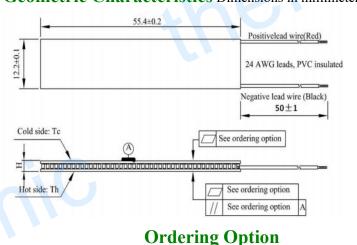
Application

- CCD Sensor
- Laser cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

Performance Specification Sheet

Th(°C)	27	50	Hot side temperature at environment: dry air, N ₂
ΔT _{max} (°C)	70	79	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side
U _{max} (Voltage)	28.7	30.9	Voltage applied to the module at DT _{max}
I _{max} (Amps)	2.32	2.32	DC current through the modules at DT _{max}
Q _{Cmax} (Watts)	42.1	45.3 Cooling capacity at cold side of the module under DT=0 °C	
AC resistance(Ohms)	9.46	10.19	The module resistance is tested under AC
Tolerance (%)	± 10		For thermal and electricity parameters

Geometric Characteristics Dimensions in millimeters



Manufacturing Options

A. Solder:

- 1. T100: BiSn (Tmelt=138°C)
- 2. T200: CuSn (Tmelt = 227 °C)

B. Sealant:

- 1. NS: No sealing (Standard)
- 2. SS: Silicone sealant
- 3. EPS: Epoxy sealant
- 4. Customer specify sealing

: Standard ceramic surface without metallizing M1: Cold Side metallizing M2: Hot Side metalizing

M3: Both Sides metallizing

C. Ceramics:

1. Alumina (Al₂O₃, white 96%)

D. Ceramics Surface Options:

2. Metallized (Au/Ni plating)

1. Blank ceramics (not metallized)

2. Aluminum Nitride (AlN)

Naming for the Module

Suffix	Thickness H	Flatness /	Lead wire length(mm)
	(mm)	Parallelism (mm)	Standard/Optional length
TF	0: 2.6±0.1	0: 0.1/0.13	50±1/Specify
TF	1: 2.6±0.05	1: 0.08/0.1	50±1/Specify
TF	2: 2.6±0.025	2: 0.05/0.08	50±1/Specify

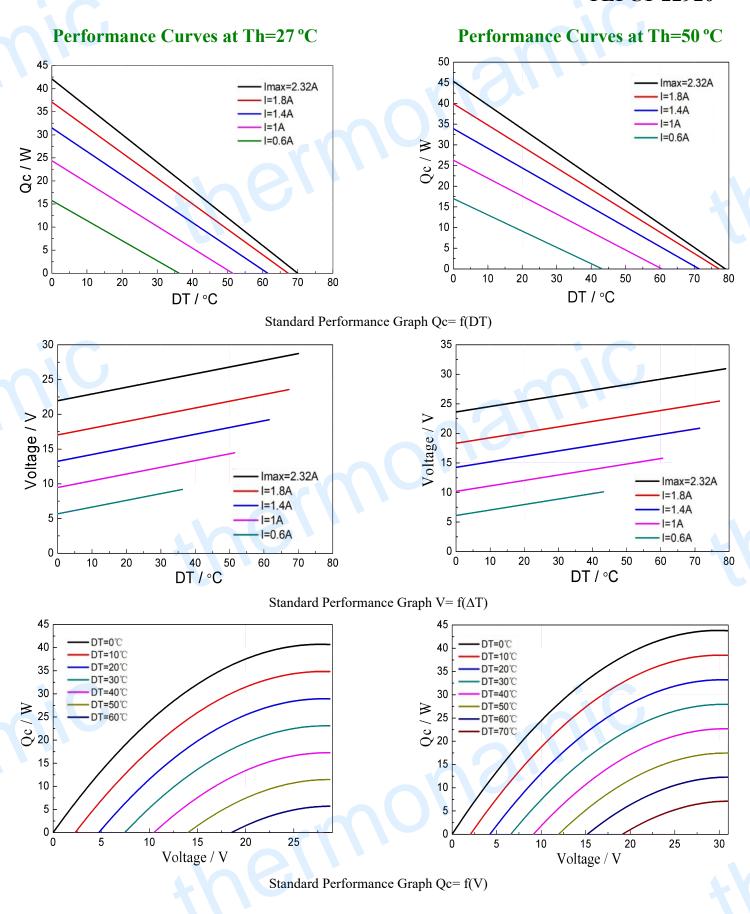
Eg. TF01: Thickness(Without plating)2.6±0.1(mm) and Flatness 0.08/0.1 (mm)

TEFC1-22920X- X-X-X-X Ceramics Flatness/ Parallelism Sealant Solder TEFC1-22920M1-T200-NS-TF01-AlO-Au T200: CuSn (Tmelt=227°C) AlO: Alumina (Al2O3, white 96%) NS: No sealing

TF01: Thickness(Without plating) ±0.1(mm) and Flatness 0.08/0.1 (mm)

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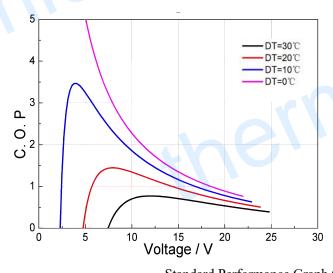


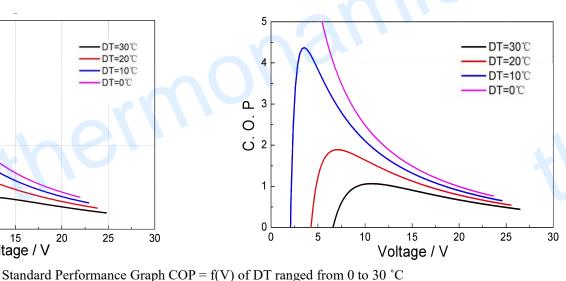
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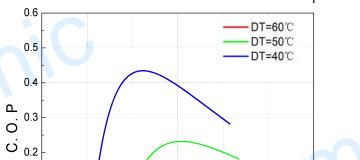
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Performance Curves at Th=50 °C

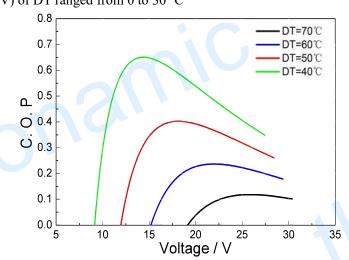






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Voltage / V



Standard Performance Graph COP = f(V) of DT ranged from 40 to 60/70 °C

Remark: The coefficient of performance (COP) is the cooling power Qc/Input power (V × I).

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Operation Cautions

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Operation below I_{max} or V_{max}
- Work under DC

0.1

0.0

Note: All specifications subject to change without notice.